



SCAS317M-NOVEMBER 1993-REVISED MARCH 2005

FEATURES

- Member of the Texas Instruments Widebus™
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- **Bus Hold on Data Inputs Eliminates the Need** for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 16-bit registered transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVCH16543A can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register, to permit independent control in either direction of data flow.

DGG, DGV, OR DL PACKAGE (TOP VIEW)

		_	_	1
1 OEAB	1	U	56	1 OEBA
1LEAB	2		55	1LEBA
1CEAB	3		54	1CEBA
GND [4		53	GND
1A1	5		52] 1B1
1A2	6		51] 1B2
V _{CC}	7		50] v _{cc}
1A3 [8		49] 1B3
1A4 [9] 1B4
1A5 [10] 1B5
GND [11		46] GND
1A6 [12		45] 1B6
1A7 [13		44] 1B7
1A8 [14		43] 1B8
2A1	15		42	2B1
2A2	16		41	2B2
2A3	17		40] 2B3
GND [18		39] GND
2A4 [19		38] 2B4
2A5 [20		37] 2B5
2A6 [21		36] 2B6
V _{CC}	22		35] v _{cc}
2A7 [23		34] 2B7
2A8 [24		33] 2B8
GND [25		32] GND
2CEAB	26		31	2CEBA
2LEAB	27		30	2LEBA
2OEAB	28		29	2 <mark>OEBA</mark>

ORDERING INFORMATION

T _A	PACKAGE	PACKAGE ⁽¹⁾		TOP-SIDE MARKING
4000 to 0500	SSOP – DL	Tube	SN74LVCH16543ADL	1.1/01/1465424
	SSOP - DL	Tape and reel	SN74LVCH16543ADLR	LVCH16543A
	TSSOP - DGG	Tape and reel	SN74LVCH16543ADGGR	LVCH16543A
–40°C to 85°C	TVSOP - DGV	Tape and reel	SN74LVCH16543ADGVR	LDH543A
	VFBGA – GQL	Tana and real	SN74LVCH16543AGQLR	LDH543A
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74LVCH16543AZQLR	LDH043A

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. Widebus is a trademark of Texas Instruments.

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the CEBA, LEBA, and OEBA inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended. The bus-hold circuitry is part of the input circuit and is not disabled by $\overline{\sf OE}$ or DIR.

GQL OR ZQL PACKAGE (TOP VIEW) 1 2 3 4 5 6 000000 Α 000000В С 000000 000000 D Е \bigcirc \bigcirc F \bigcirc \bigcirc G 000000000000 Н 000000 J 000000 Κ

TERMINAL ASSIGNMENTS

	1	2	3	4	5	6
Α	1CEAB	1 LEAB	1 <mark>OEAB</mark>	1 <mark>OEBA</mark>	1LEBA	1CEBA
В	1A2	1A1	GND	GND	1B1	1B2
С	1A4	1A3	V _{CC}	V _{CC}	1B3	1B4
D	1A6	1A5	GND	GND	1B5	1B6
E	1A8	1A7			1B7	1B8
F	2A1	2A2			2B2	2B1
G	2A3	2A4	GND	GND	2B4	2B3
Н	2A5	2A6	V _{CC}	V _{CC}	2B6	2B5
J	2A7	2A8	GND	GND	2B8	2B7
K	2 CEAB	2 LEAB	2 OEAB	2 OEBA	2 LEBA	2 CEBA





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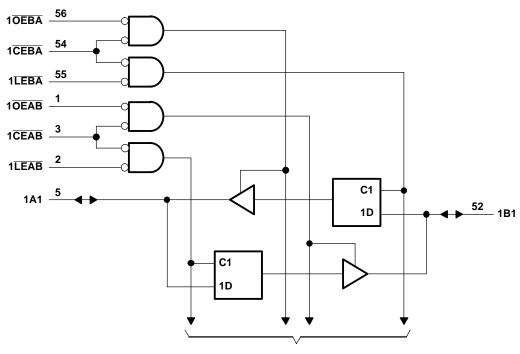
FUNCTION TABLE⁽¹⁾ (EACH 8-BIT SECTION)

	INPUTS					
CEAB	LEAB	OEAB	Α	В		
Н	Χ	X	Χ	Z		
X	Χ	Н	X	Z		
L	Н	L	X	B ₀ ⁽²⁾		
L	L	L	L	L		
L	L	L	Н	Н		

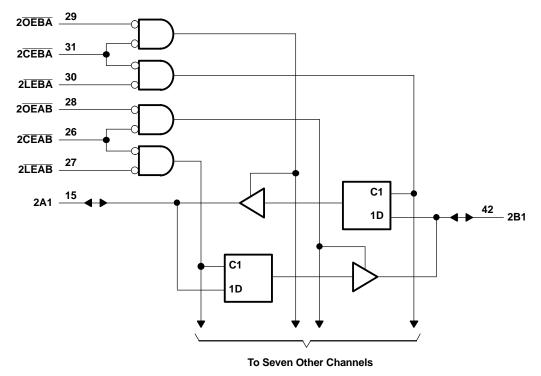
- (1) A-to-B data flow is shown; B-to-A flow control is the same, except that it uses CEBA, LEBA, and OEBA.
 (2) Output level before the indicated steady-state input conditions were
- established



LOGIC DIAGRAM (POSITIVE LOGIC)



To Seven Other Channels



Pin numbers shown are for the DGG, DGV, and DL packages.



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impeda	ance or power-off state (2)	-0.5	6.5	V
Vo	Voltage range applied to any output in the high or low	state ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GND			±100	mA
		DGG package		64	
0	Decke so thermal impedance (4)	DGV package		48	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	DL package		56	-C/VV
		GQL/ZQL package		42	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
\/	Cumply valtage	Operating	1.65	3.6	V	
V _{CC}	Supply voltage	Data retention only	1.5		V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
V_{I}	Input voltage		0	5.5	V	
\/	Output voltage	High or low state	0	V _{CC}	V	
Vo	Output voltage	3-state	0	5.5	v	
		V _{CC} = 1.65 V		-4		
	High level output ourrent	V _{CC} = 2.3 V		-8	mA	
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12	ША	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Low level output ourrent	V _{CC} = 2.3 V		8	mA	
l _{OL}	Low-level output current	V _{CC} = 2.7 V		12	IIIA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T_A	Operating free-air temperature		-40	85	°C	

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

SN74LVCH16543A 16-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	UNIT	
		$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V _{CC} - 0.2			
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
V _{OH}		$I_{OH} = -8 \text{ mA}$	2.3 V	1.7		V	
		I _{OH} = -12 mA	2.7 V	2.2		V	
		1 _{OH} = -12 IIIA	3 V	2.4			
		$I_{OH} = -24 \text{ mA}$	3 V	2.2			
		I _{OL} = 100 μA	1.65 V to 3.6 V		0.2		
		I _{OL} = 4 mA	1.65 V		0.45		
V_{OL}		I _{OL} = 8 mA	2.3 V		0.7	V	
		I _{OL} = 12 mA	2.7 V		0.4		
		I _{OL} = 24 mA	3 V		0.55		
I _I	Control inputs	V _I = 0 to 5.5 V	3.6 V		±5	μΑ	
I _{off}		V_I or $V_O = 5.5 \text{ V}$	0		±10	μΑ	
		V _I = 0.58 V	1.65 V	(2)			
		V _I = 1.07 V	1.03 V	(2)			
		V _I = 0.7 V	2.3 V	45			
$I_{I(hold)}$	A or B ports	V _I = 1.7 V	2.3 V	-45		μΑ	
		$V_1 = 0.8 \text{ V}$	3 V	75			
		V _I = 2 V	3 V	-75			
		$V_1 = 0 \text{ to } 3.6 \text{ V}^{(3)}$	3.6 V		±500		
$I_{OZ}^{(4)}$		$V_O = 0 \text{ V or } (V_{CC} \text{ to } 5.5 \text{ V})$	2.3 V to 3.6 V		±5	μΑ	
		$V_I = V_{CC}$ or GND, $I_O = 0$	261/		20	^	
I _{CC}		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{(5)}, \qquad \qquad \text{I}_{\text{O}} = 0$	3.6 V		20	μΑ	
ΔI_{CC}		One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND	2.7 V to 3.6 V		500	μΑ	
C_{i}	Control inputs	$V_I = V_{CC}$ or GND	3.3 V		5	pF	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	3.3 V		8	pF	

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = ± 0.1	1.8 V $V_{CC} = 2.5 \text{ V}$ 5 V $\pm 0.2 \text{ V}$		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE or CE low	(1)		(1)		3.3		3.3		ns
t _{su}	Setup time, data before LE or CE↓	(1)		(1)		1.1		1.1		ns
t _h	Hold time, data after LE or CE↓	(1)		(1)		1.9		1.9		ns

⁽¹⁾ This information was not available at the time of publication.

All typical values are at V_{CC} = 3.3 V, T_A = 25°C. This information was not available at the time of publication.

This is the bus-hold maximum dynamic current required to switch the input from one state to another.

For the total leakage current in an I/O port, consult the $I_{I(hold)}$ specification for the input voltage condition, $0 \text{ V} < V_I < V_{CC}$, and the I_{OZ} specification for the input voltage conditions, $V_I = 0 \text{ V}$ or $V_I = V_{CC}$ to 5.5 V. The bus-hold current, at input voltage greater than V_{CC} , is negligible.

This applies in the disabled state only.

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Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V_{CC} = 2.5 V \pm 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INFOT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	A or B	B or A	(1)	(1)	(1)	(1)		6.1	1.2	5.4	20
t _{pd}	ĪĒ	A or B	(1)	(1)	(1)	(1)		7.4	1.5	6.1	ns
t _{en}	CE	A or B	(1)	(1)	(1)	(1)		7.9	1.2	6.6	20
t _{dis}	CE	AUIB	(1)	(1)	(1)	(1)		7.1	1.5	6.6	ns
t _{en}	ŌĒ	A or D	(1)	(1)	(1)	(1)		7.6	1	6.3	20
t _{dis}	OE .	A or B	(1)	(1)	(1)	(1)		6.9	1.5	6.3	ns

⁽¹⁾ This information was not available at the time of publication.

Operating Characteristics

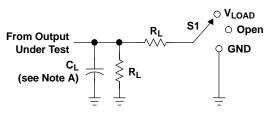
 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT	
C	Power dissipation capacitance	Outputs enabled	f = 10 MHz	(1)	(1)	44	nE
C_{pd}	per transceiver	Outputs disabled	T = TO MINZ	(1)	(1)	4	p⊦

⁽¹⁾ This information was not available at the time of publication.



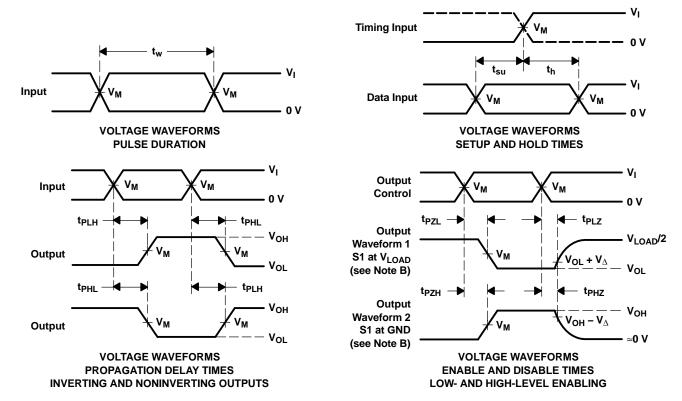
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	INF	PUTS	.,	V	_		V
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	V_{Δ}
1.8 V ± 0.15 V	v _{cc}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

27-Sep-2007

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVCH16543ADGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16543ADGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16543ADGVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16543ADGVRG4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCH16543ADLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543ADGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543ADGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543ADL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543ADLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543ADLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCH16543AGQLR	NRND	BGA MI CROSTA R JUNI OR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVCH16543AZQLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

27-Sep-2007

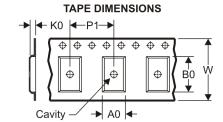
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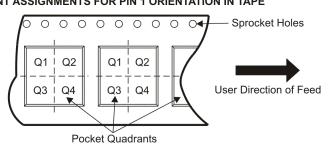
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVCH16543ADGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVCH16543ADGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1
SN74LVCH16543ADLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
SN74LVCH16543AGQLR	BGA MI CROSTA R JUNI OR	GQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
SN74LVCH16543AZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1

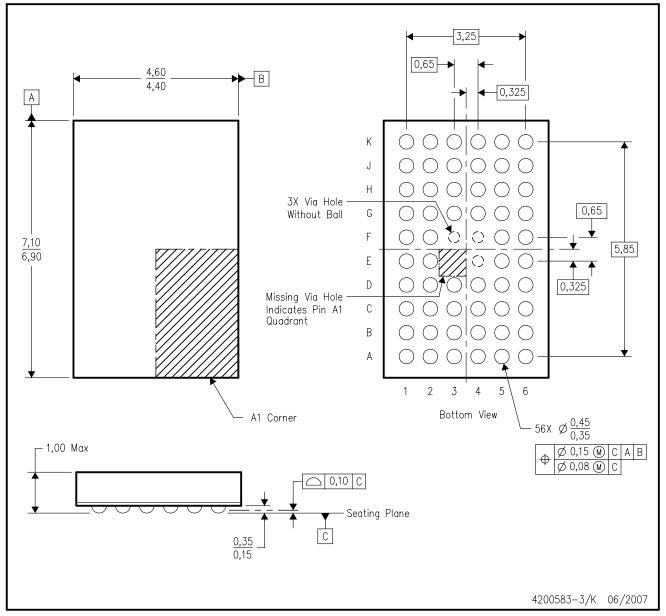


*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVCH16543ADGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74LVCH16543ADGVR	TVSOP	DGV	56	2000	346.0	346.0	41.0
SN74LVCH16543ADLR	SSOP	DL	56	1000	346.0	346.0	49.0
SN74LVCH16543AGQLR	BGA MICROSTAR JUNIOR	GQL	56	1000	346.0	346.0	33.0
SN74LVCH16543AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	346.0	346.0	33.0

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



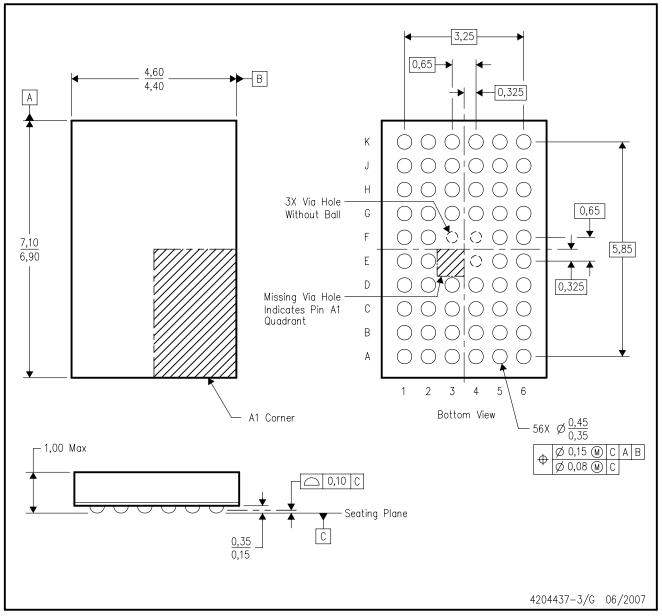
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

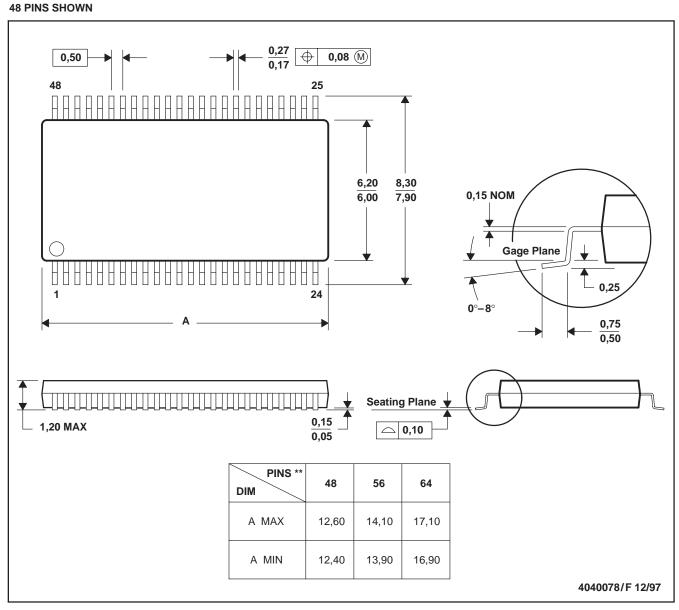
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



DGG (R-PDSO-G**)

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PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

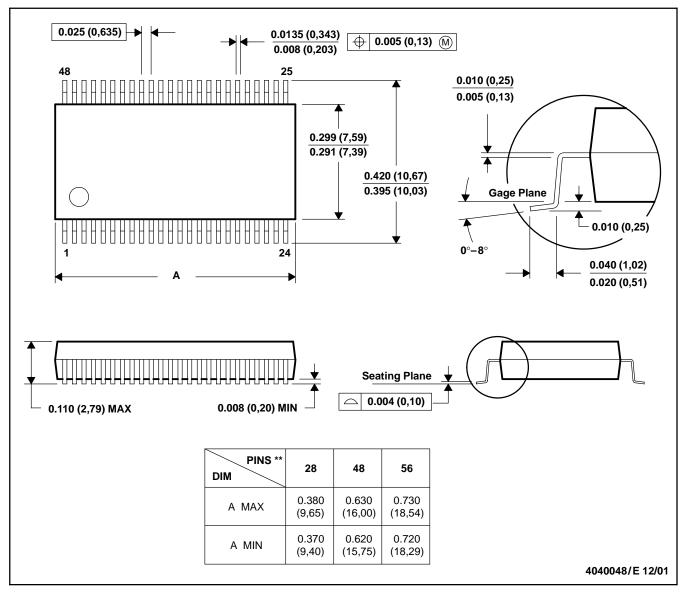
C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



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